
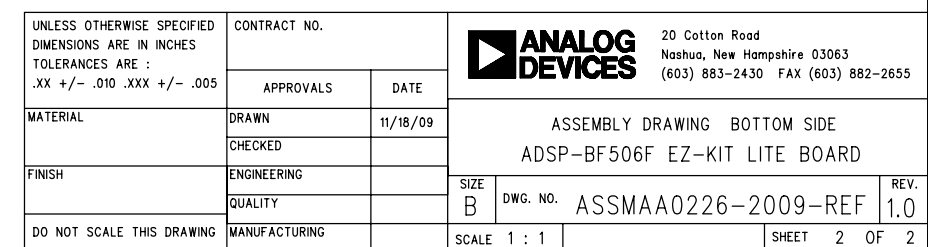
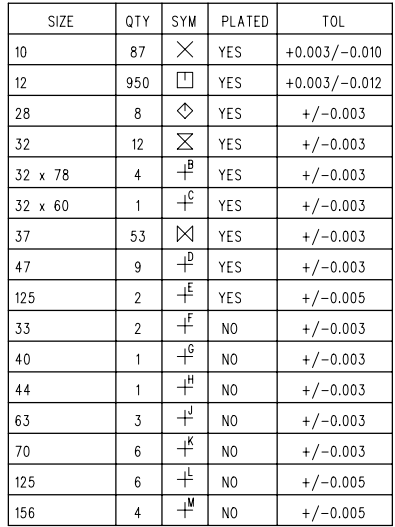


ASSEMBLY NOTES:

1. MASK HOLES FOR TP1-TP8 BEFORE SOLDERING.
2. BREAK OFF STRIP AT COMPLETION OF ASSEMBLY.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		 20 Cotton Road Nashua, New Hampshire 03063 (603) 883-2430 FAX (603) 882-2655
	APPROVALS	DATE	
	DRAWN	11/18/09	ASSEMBLY DRAWING TOP SIDE ADSP-BF506F EZ-KIT LITE BOARD
	CHECKED		
MATERIAL	ENGINEERING		SIZE B DWG. NO. ASSMAA0226-2009-REF 1.0
FINISH	QUALITY		
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1 SHEET 1 OF 2





BOARD TO BE FABRICATED PER IPC-6012A, CLASS 2.

MATERIAL: POLYCLAD FR-370HR OR EQUIVALENT. OUTER LAYERS 1/2 OZ/SQFT CU  
INNER LAYERS 1/2 OZ/SQFT CU FINISHED .062 (.055 MIN .070 MAX SEE DETAIL).  
VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.

PLATING: ADDITIONAL CU PLATING 1/2 OZ/SQFT  
ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND.  
MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE  
PER IPC-6012A WITH AMENDMENT 1, CLASS 2 REQUIREMENTS.  
WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.

FINISH: SURFACES TO BE COATED BY ENIG OF 2 TO 10 MICROINCHES OVER  
A MINIMUM OF 60-200 MICROINCHES OF LOW STRESS NICKEL.

SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES.  
PHOTOPLOT FILES HAVE PAD SIZE SAME SIZE AS ETCHED PAD (1/1).  
VENDOR MAY ADJUST SOLDERMASK PAD SIZE AS NEEDED.

SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.

ARTWORK: MINIMUM FEATURE SIZE = 0.005  
MINIMUM AIR GAP = 0.0049

ALL DIMENSIONS ARE IN INCHES.

CONTROLLED IMPEDANCE: BOARD TO BE BUILT TO YIELD CONTROLLED IMPEDANCE  
OF 60 OHMS +/- 10% ON ALL .005" LINE WIDTHS

THEVING IS ALLOWED, UNLESS OTHERWISE SPECIFIED.

VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS.  
METHOD 1 IS PREFERRED.  
METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER  
ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE  
FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERTURES BOTH SIDES.  
METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/IMMERSION  
GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS  
LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.

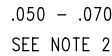
VIA HOLES (.006, .010, .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.


TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.

USE IPC-D-356 NETLIST AS SUPPLIED FOR CHECKING.  
THERE IS 1 INTENTIONAL SHORTS ON LAYER 1  
GND AND PGND AT W1  
PLEASE IGNORE THESE WHEN COMPARING THE IPC-356 NETLIST AND GERBERS.  
CONTACT ANALOG DEVICES IF ANY OTHER DISCREPANCIES ARE FOUND.

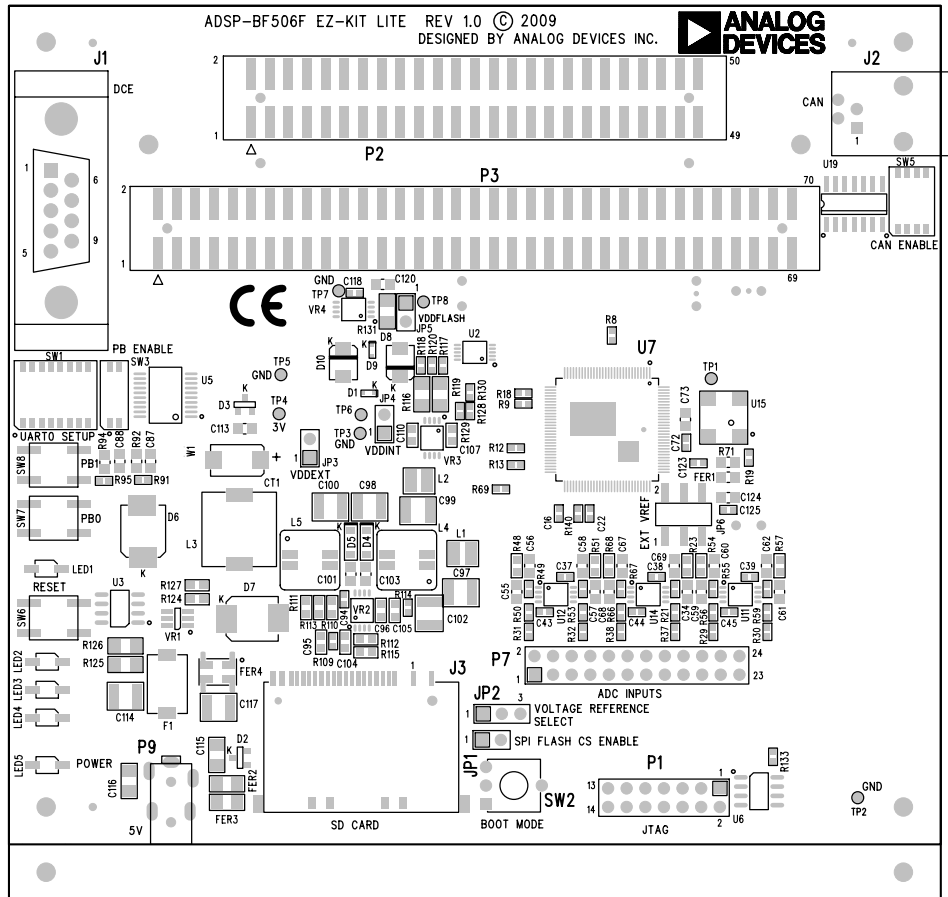
V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.

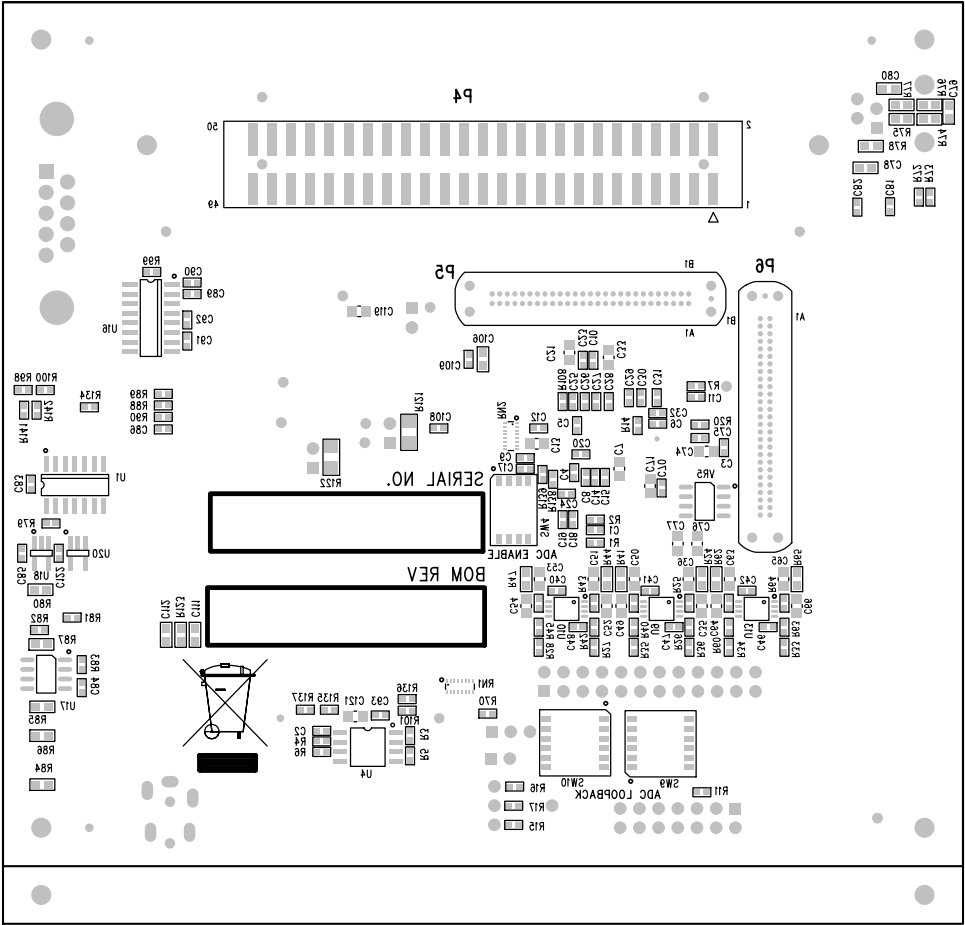
BUILD AS 1-UP PCB.

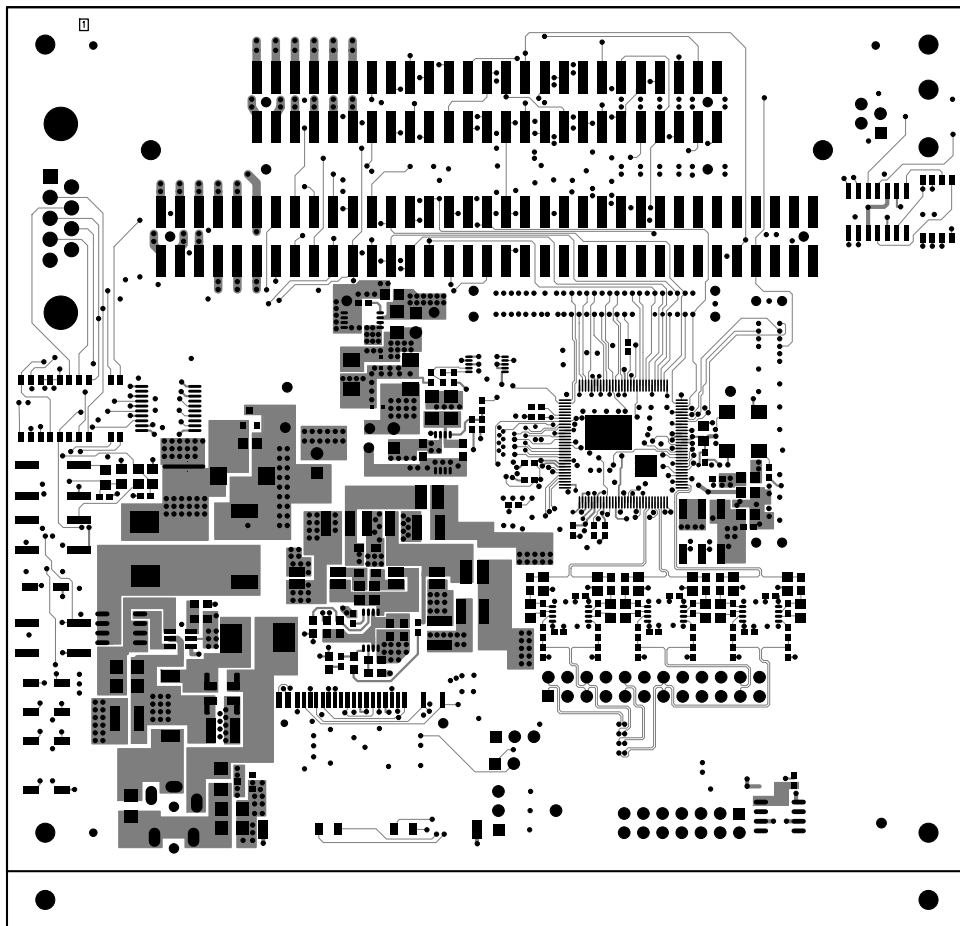


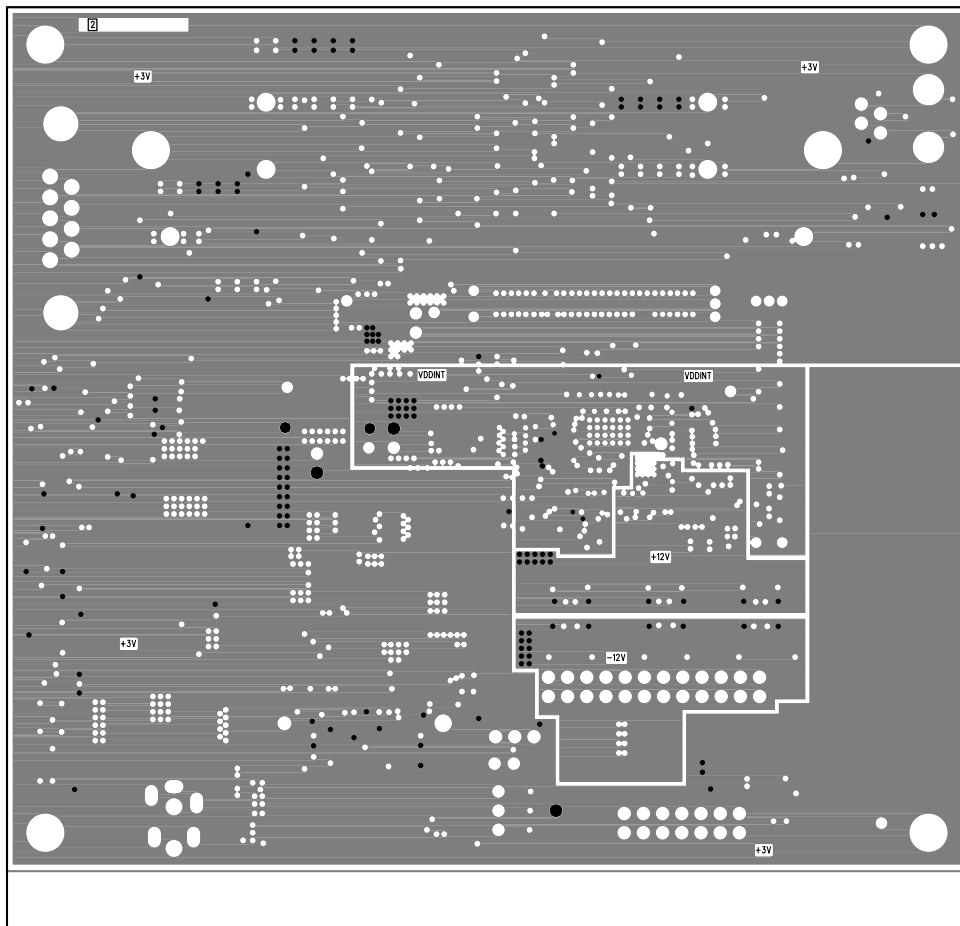
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005		CONTRACT NO.		 <b>ANALOG DEVICES</b> 20 Cotton Road Nashua, New Hampshire 03063 (603) 883-2430 FAX (603) 882-2655		
		APPROVALS	DATE			
MATERIAL	SEE NOTES	DRAWN	11/18/09	FABRICATION DRAWING ADSP-BF506F EZ-KIT LITE BOARD		
		CHECKED				
FINISH	SEE NOTES	ENGINEERING				
		QUALITY		SIZE B	DWG. NO. A0226-2009-REF	REV. 1.0
DO NOT SCALE THIS DRAWING	MANUFACTURING			SCALE 1 : 1		SHEET 1 OF 18

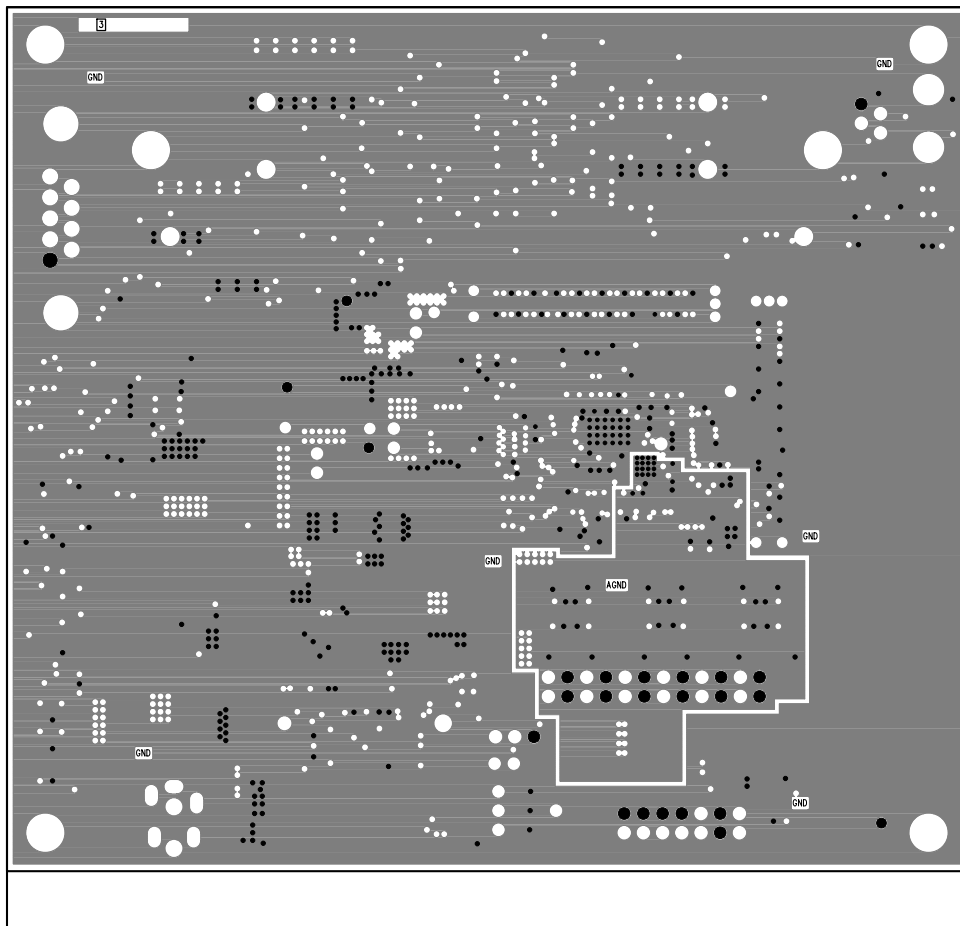
ADSP-BF506F EZ-KIT LITE REV 1.0 © 2009  
DESIGNED BY ANALOG DEVICES INC.



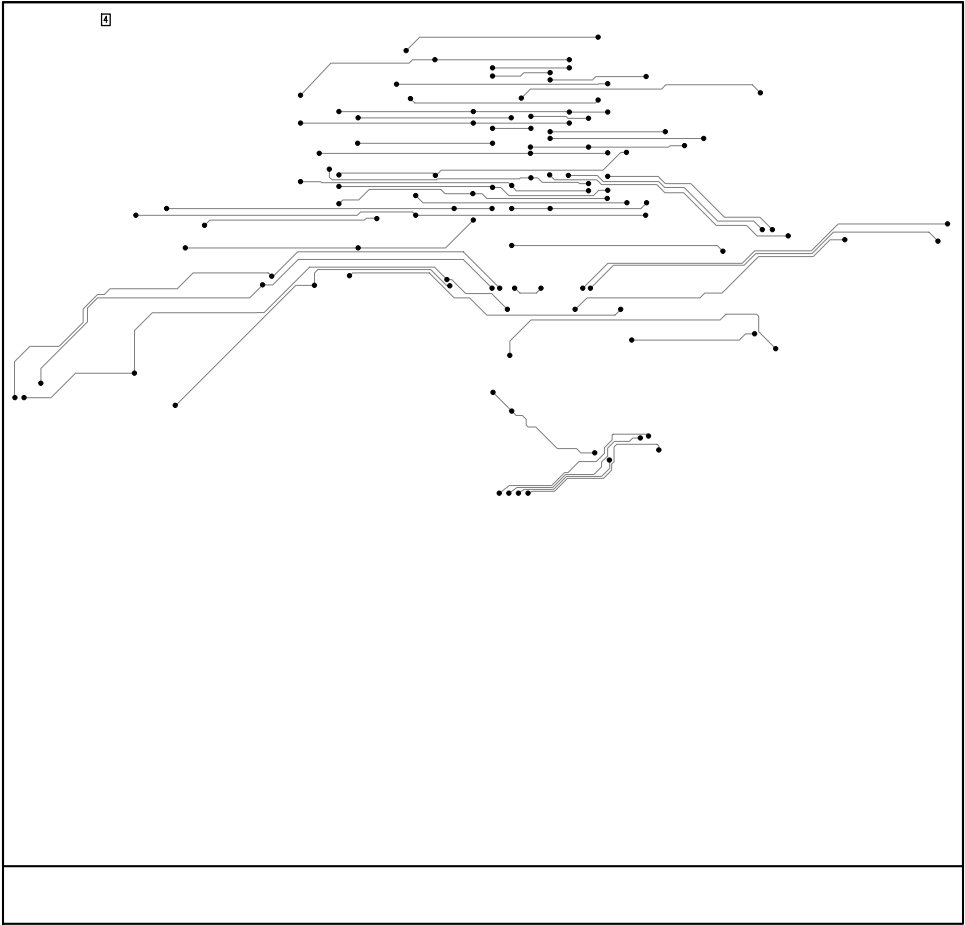


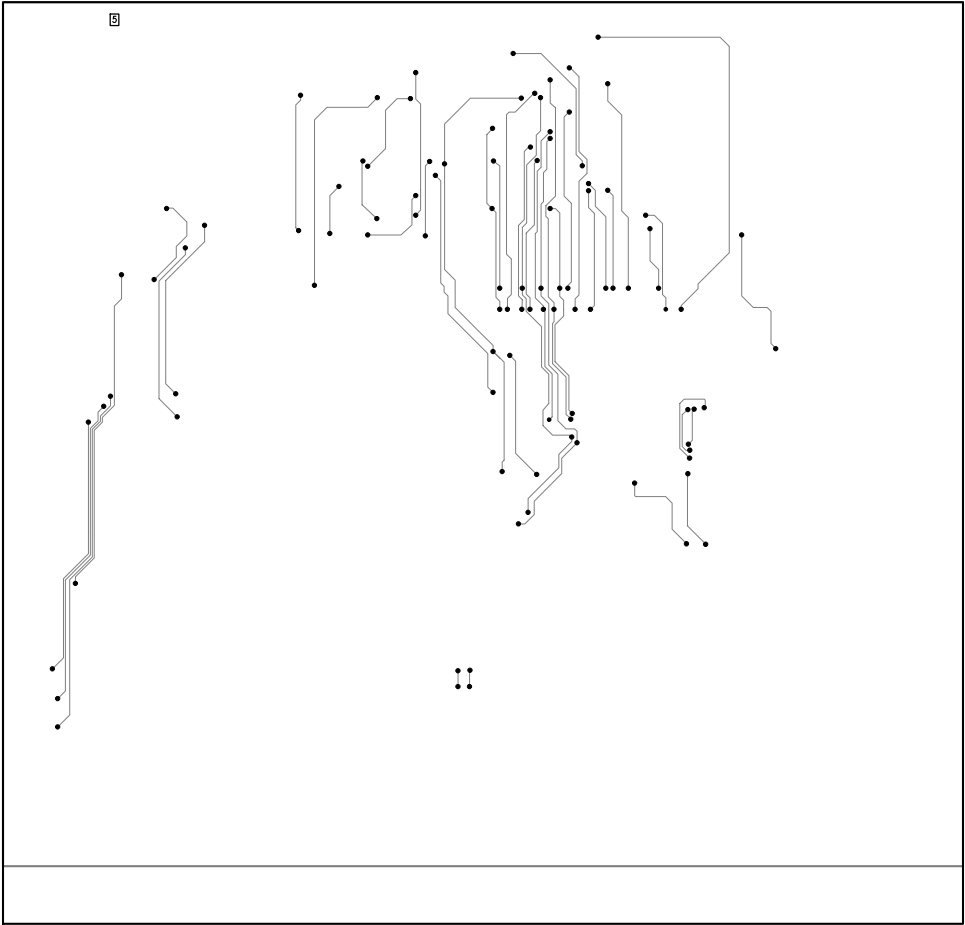


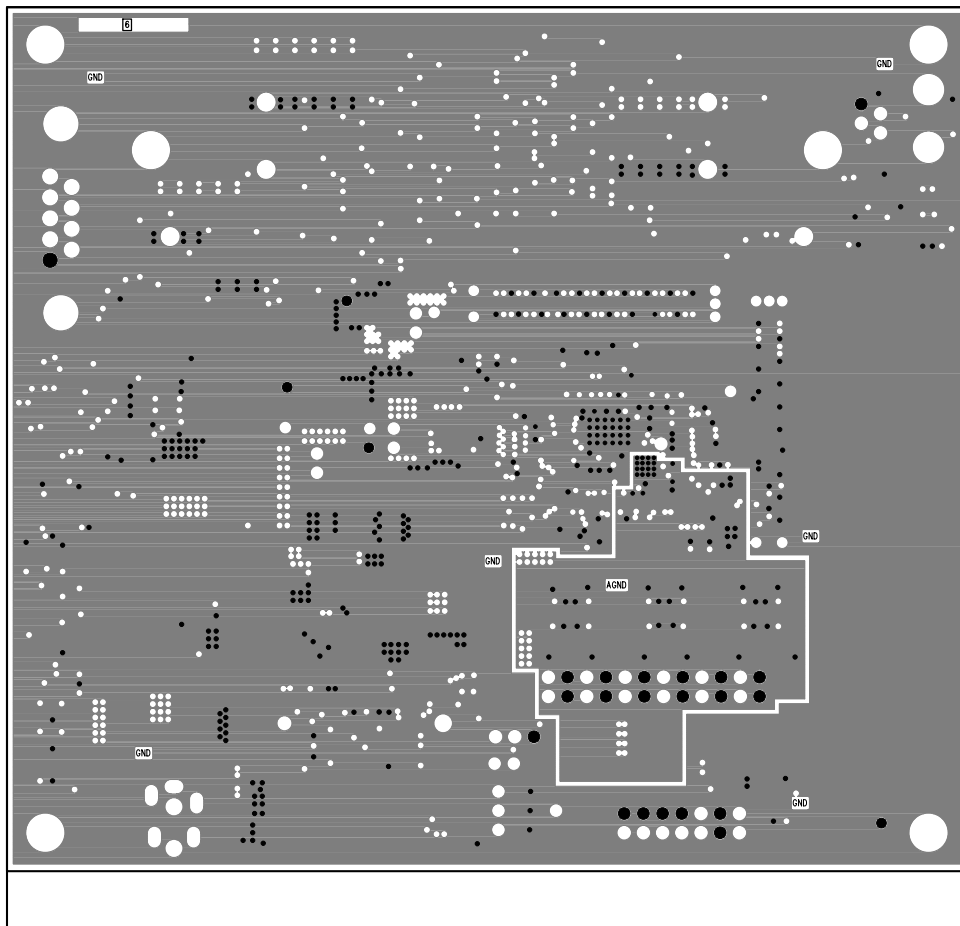


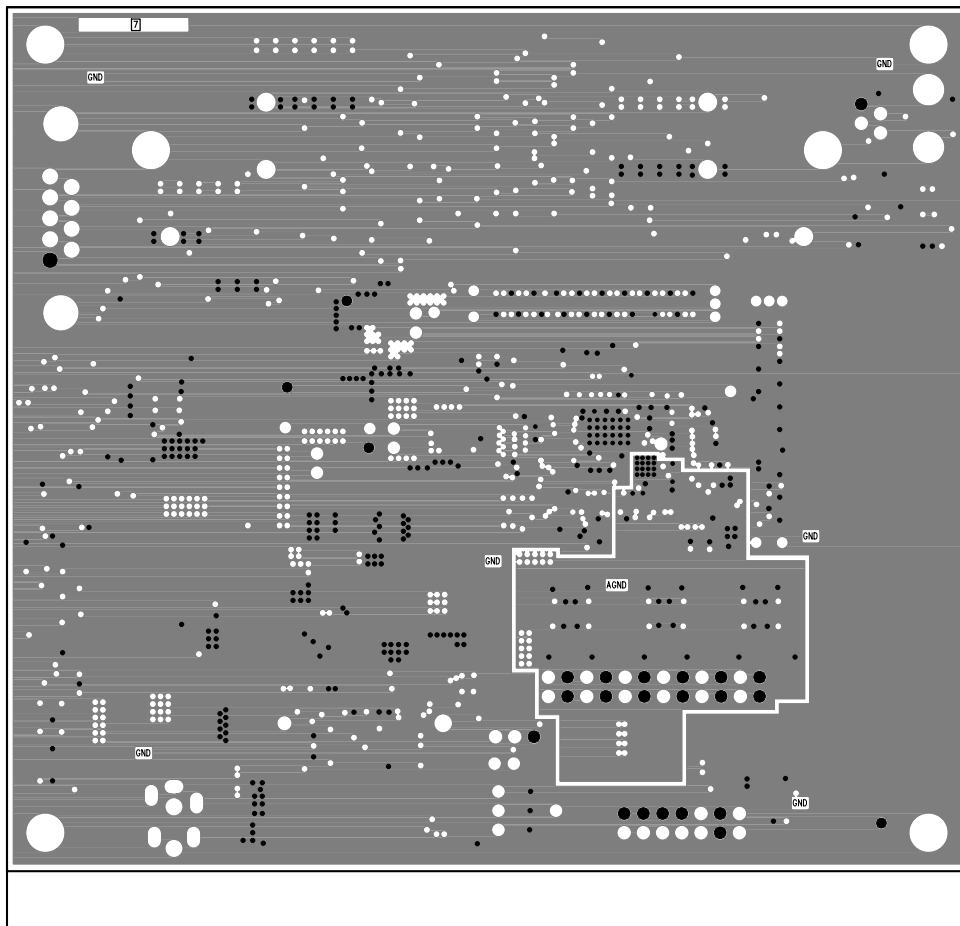












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